



Eccoshield® VY-81

RF Conductive Caulking Compound and Sealer

RF CONDUCTIVE CAULKING COMPOUND AND SEALER

Eccoshield VY-81 is a single-component electrically conductive non-hardening compound of metallic particles. It is similar to but different from our Eccoshield® VY product, in that the VY-81 has an increased volume resistivity (decreased conductivity). It also has a lower density than Eccoshield VY and is more cost effective to use per pound. Once applied, Eccoshield VY-81 assures long-term integrity of the shielding enclosure and will prevent corrosion in the contact area. Due to high tack and non-hardening characteristics, Eccoshield VY-81 will function under vibration and displacement due to temperature changes. It is fast and economical to use.

FEATURES AND BENEFITS

MARKETS

- maintains good shielding effectiveness due to non-hardening characteristic of material
 material can be applied using conventional
- Commercial Telecom
- Test and Measurement
- Security and Defense

SPECIFICATIONS

caulking equipment

| TYPICAL PROPERTIES | ECCOSHIELD VY-81 |
|-------------------------------------|-------------------------|
| Service Temperature °C (°F) | -54 to 205 (-65 to 400) |
| Volume Resistivity Ohm-cm | 0.01 |
| Density g/cc | 1.80 |
| Shielding effectiveness dB | 80 - 90 |
| Length of 3mm diam. bead/lb, m (ft) | 32 (105) |

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

APPLICATIONS

- Eccoshield VY-81 is specifically designed for use as a shielding effective material for EMI/RF protection on structures, cabinets, conduits, modules and components.
- Joints, seams, threads, cracks, and other RF leakage sources can be effectively plugged.

AVAILABILITY

• Eccoshield VY-81 is sold by the pound in one pound (16 oz.) jars.

INSTRUCTIONS FOR USE

- Eccoshield VY-81 can be used with conventional caulking equipment to develop fast and uniform-weight beads. It can also be applied by spatula, putty knife, plastic syringe applicators, or other suitable tools such as caulking guns. For spatula application, small amount of methyl ethyl ketone (MEK) can be added to adjust consistency.
- All surfaces for application should be prepared by removing rust, scale, non-conductive oxides and dirt. Wire brushing and/or solvent cleaning is usually adequate. Surfaces should be bright and electrically conductive.

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- Apply Eccoshield VY-81 to the prepared surface using a syringe, caulking gun, or spatula. Lap joints may be made immediately. Excess and spillage may be collected and reused. Hardened or thick material can be reactivated by the addition of small amounts of methyl ketone.
- For cleanup, acetone or trichloroethylene are suitable.

Caution: Eccoshield VY-81 contains flammable solvents. Keep away from heat and open flames. When not in use, keep sealed to avoid evaporation. The handling of these products should present no problems if ordinary care is exercised to avoid breathing vapors, the skin is protected against contamination, swallowing is avoided, and eyes are protected.

RFP-DS-VY-81 031016

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